

ABSTRACT

5 A rectangular frame-like auxiliary
substrate for hierarchical mounting 14 is mounted so
as to surround a semiconductor component 15 mounted
on a printed wiring board 11, and another
semiconductor component 16 is mounted above the
semiconductor component 15, being supported on the
auxiliary substrate for hierarchical mounting 14
10 with terminals of the semiconductor component 16
being connected thereto. The auxiliary substrate
for hierarchical mounting 14 has wiring patterns 35a
and through holes 34a, and includes a power supply
layer 32 and a ground layer 33 inside thereof with
15 printed wiring board pads on a lower surface of the
auxiliary substrate for hierarchical mounting 14
being more dispersed than component pads 23a on an
upper surface of the auxiliary substrate for
hierarchical mounting 14. Therefore, a gap space 41
20 between each adjacent ones of pads 40a on the
printed wiring board 11 which gap space 41
corresponds to the semiconductor component 16 is
widened so that a wiring pattern 43 extending
outward on the printed wiring board from a pad 21a
25 connected to the semiconductor component 15 passes
through the gap space 41 without difficulty.